

# University of Miami

## ECE 414 Computer Organization and Design

### EXPERIMENT #1 MULTIPLEXER DESIGN

**Submitted by:** Brandon Rubio, Isabela Bandrich, Rainier Young, Nikeem Dunkelly-Allen

**On:** 9/16/22

**to :** Dr. Onur Tigli

#### Objective

The goal of this lab is to use structural and dataflow design techniques in Verilog to instantiate and test the proper operation of several multiplexer units. The Xilinx ISE tools software will be used for: coding, verification, simulation, synthesis, and timing analysis. For the purpose of demonstrating proper operation, verified designs will be implemented using Digilent's Nexys-4 FPGA boards[1].

#### Verilog HDL and Testbench Code

##### Mux 2-to-1:

- **Structural Design Verilog Code:**

```
21 module Mux_2to1(  
22     input [1:0] In,  
23     input S,  
24     output Out  
25 );  
26     wire a, b, c;  
27  
28     and(a, In[1], S);  
29     not(c, S);  
30     and(b, In[0], c);  
31     or(Out, a, b);  
32  
33 endmodule
```

- **Dataflow Design Verilog Code:**

```

21 module DF_Mux_2to1(
22     input [1:0] In,
23     input S,
24     output Out
25 );
26     assign Out = (S)?In[1]:In[0];
27
28 endmodule

```

- **Testbenches (Same (except for module names) for both Structural and Dataflow Design):**

```
module tb_Mux_2to1;
```

```

// Inputs
reg [1:0] In;
reg S;

```

```

// Outputs
wire Out;

```

```
// Instantiate the Unit Under Test (UUT)
```

```

Mux_2to1 uut (
    .In(In),
    .S(S),
    .Out(Out)
);

```

```
initial begin
```

```

    // Initialize Inputs
    In = 0;
    S = 0;

```

```

    // Wait 100 ns for global reset to finish
    #100

```

```

    In = 0;
    S = 0;
    #100;

```

```

    In = 1;
    S = 0;
    #100;

```

```

    In = 2;
    S = 0;
    #100;

```

```

    In = 3;

```

```
S = 0;  
#100
```

```
In = 0;  
S = 1;  
#100
```

```
In = 1;  
S = 1;  
#100;
```

```
In = 2;  
S = 1;  
#100;
```

```
In = 3;  
S = 1;  
#100;
```

```
end
```

```
endmodule
```

#### **Mux 4-to-1:**

- **Verilog Code:**

```

21 module Mux_ST_2to1(
22     input [1:0] In,
23     input S,
24     output Out
25 );
26 wire a, b, c;
27 and(a, In[1], S);
28 not(c, S);
29 and(b, In[0], c);
30 or(Out, a, b);
31 endmodule
32
33 module Mux_DF_2to1(
34     input [1:0] In,
35     input S,
36     output Out
37 );
38 assign Out=(S)?In[1]:In[0];
39 endmodule
40
41 module MUX_4to1(
42     input [3:0] In,
43     input [1:0] S,
44     output Out
45 );
46 wire d, e;
47 wire [1:0] f;
48 Mux_DF_2to1 m1(In[3:2],S[0],d);
49 Mux_DF_2to1 m2(In[1:0],S[0],e);
50 assign f = {d,e};
51 Mux_ST_2to1 m3(f,S[1],Out);
52 endmodule

```

- Testbench:

```

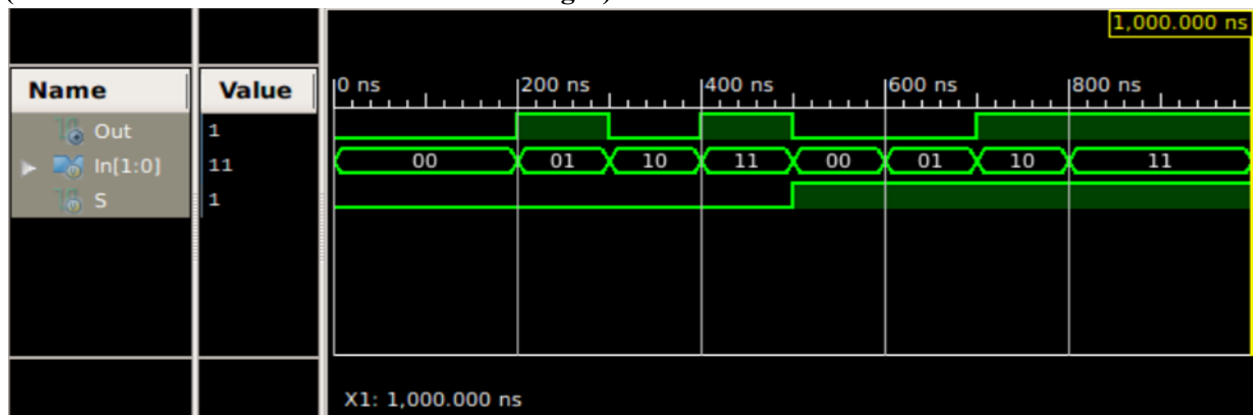
25 module tb_MUX_4to1;
26
27     // Inputs
28     reg [3:0] In;
29     reg [1:0] S;
30
31     // Outputs
32     wire Out;
33
34     // Instantiate the Unit Under Test (UUT)
35     MUX_4to1 uut (
36         .In(In),
37         .S(S),
38         .Out(Out)
39     );
40
41     reg [2:0] i; //for S bits
42     reg [4:0] j; //for In bits
43     initial begin
44         // Initialize Inputs
45         In = 0;
46         S = 0;
47
48         // Wait 100 ns for global reset to finish
49         #100;
50
51         // Add stimulus here
52         for (i = 0; i < 4; i = i + 1) begin
53             S = i;
54             for (j = 0; j < 16; j = j + 1) begin
55                 In = j;
56                 #10;
57             end
58         end
59     end
60
61 endmodule
62

```

## Simulation Results

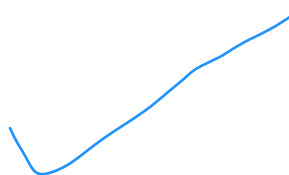
### Mux 2-to-1:

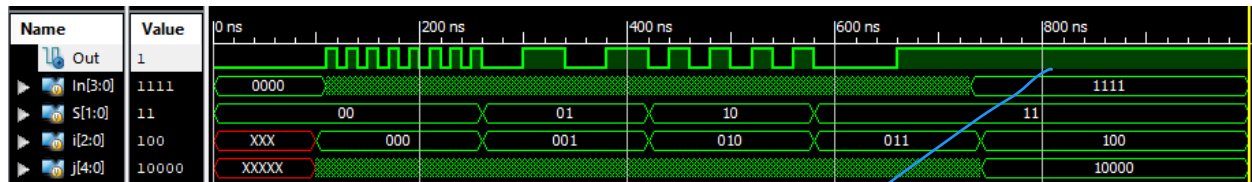
(Same for both Structural and Dataflow designs)



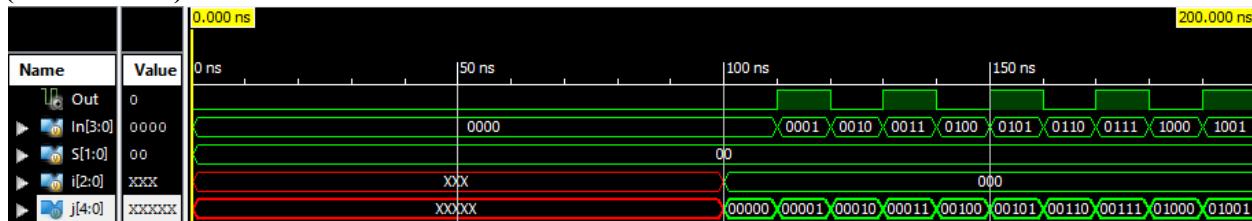
### Mux 4-to-1:

(Overview)

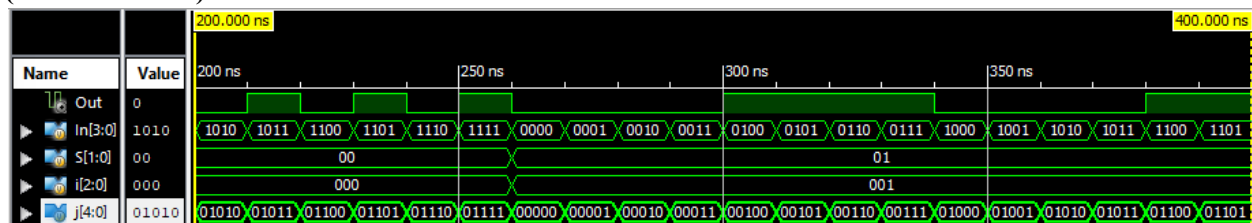




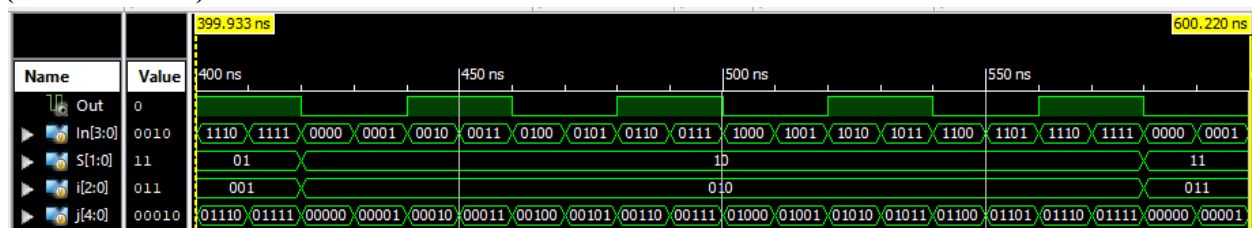
(0ns to 200 ns)



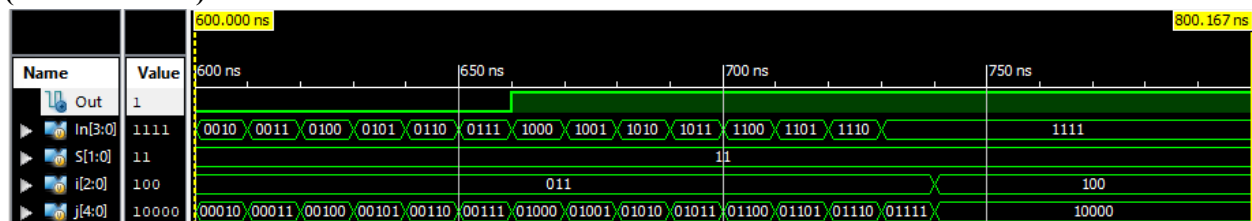
(200ns to 400ns)



(400ns to 600ns)



(600ns to 800ns)



## Device Utilization Summary

Mux 2-to-1:  
(Same for both Structural and Dataflow designs)

Device Utilization Summary (estimated values)			[-]
Logic Utilization	Used	Available	Utilization
Number of Slice LUTs	1	63400	0%
Number of fully used LUT-FF pairs	0	1	0%
Number of bonded IOBs	4	210	1%

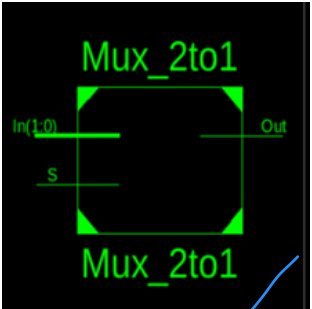
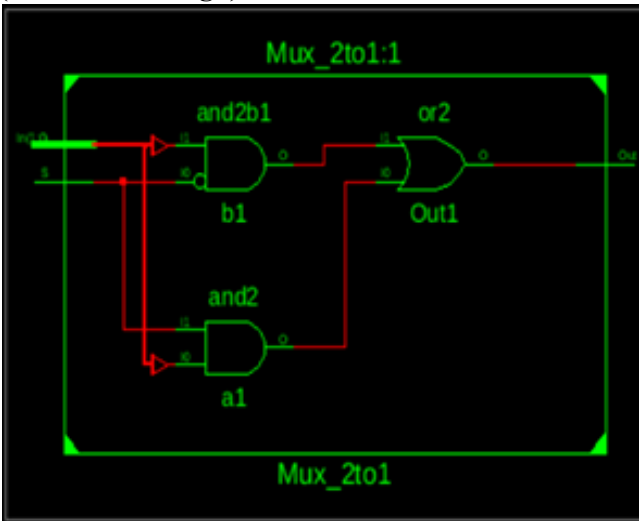
Mux 4-to-1:

Device Utilization Summary (estimated values)			[-]
Logic Utilization	Used	Available	Utilization
Number of Slice LUTs	1	63400	0%
Number of fully used LUT-FF pairs	0	1	0%
Number of bonded IOBs	7	170	4%

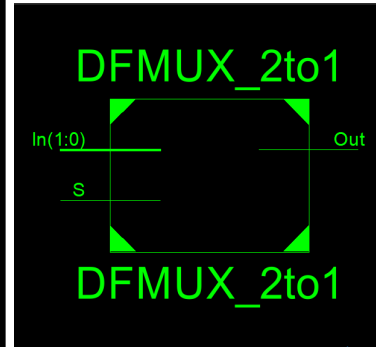
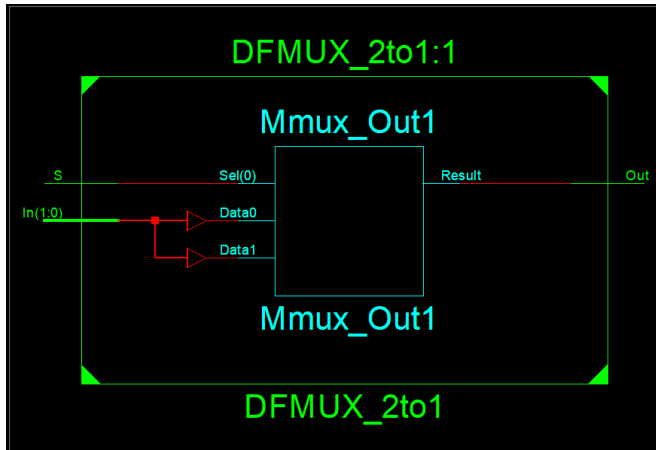
# RTL Schematic and Technology Schematic

Mux 2-to-1:

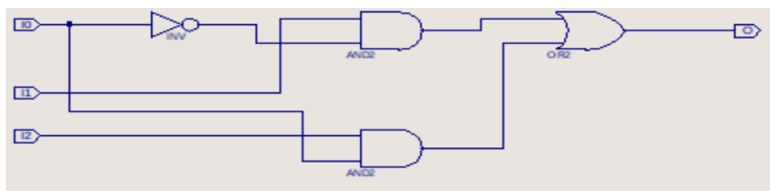
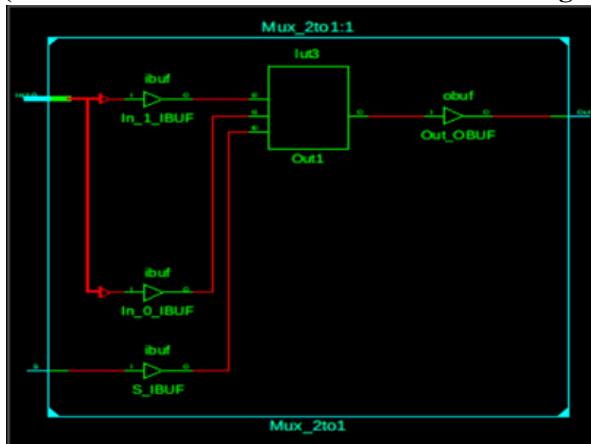
- RTL Schematic:  
(Structural Design)



(DataFlow Design)



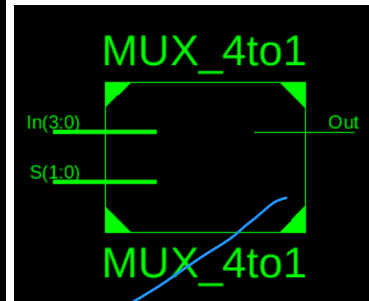
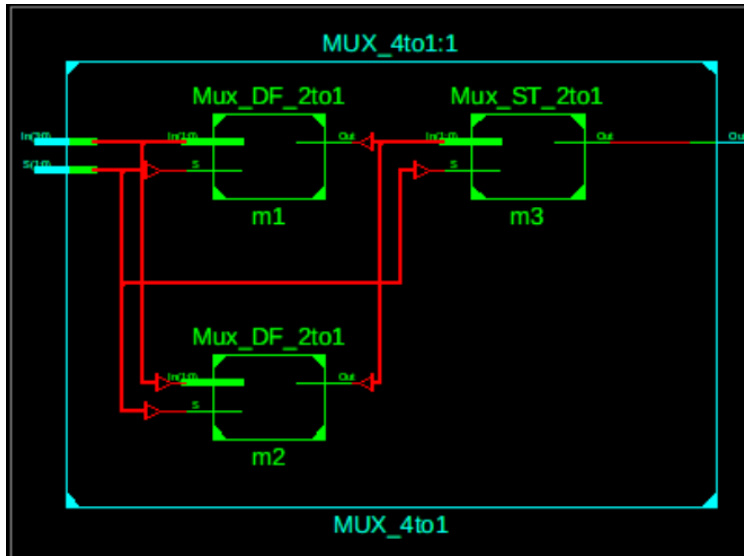
- **Technology Schematic:**  
(Same for both Structural and Dataflow designs)



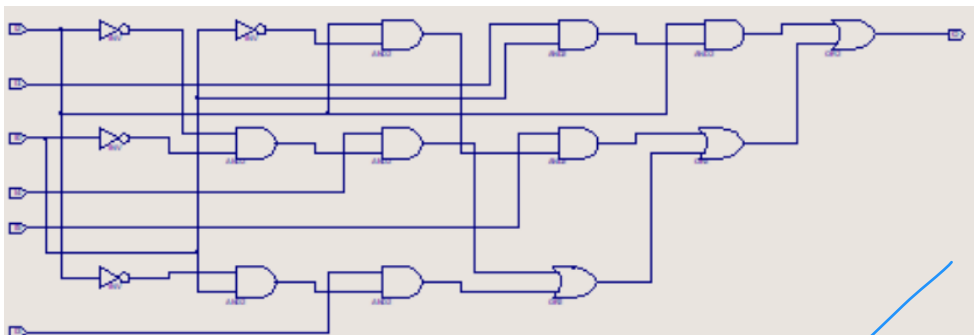
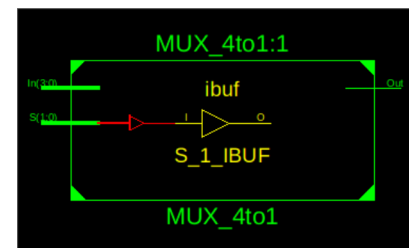
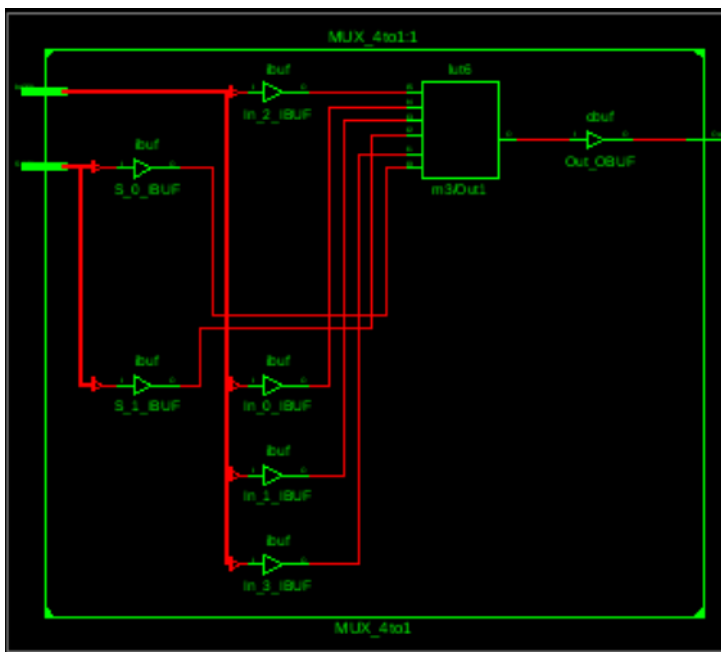
**Mux 4-to-1:**

- **RTL Schematic:**





- Technology Schematic:



## Post Place and Route Static Timing

### Mux 2-to-1: (Structural Design)

```
=====
Timing constraint: TS_pad2pad = MAXDELAY FROM TIMEGRP "inputs" TO TIMEGRP "outputs" 20 ns;
For more information, see From:To \(Multicycle\) Analysis in the Timing Closure User Guide (UG612).
3 paths analyzed, 1 endpoint analyzed, 0 failing endpoints
0 timing errors detected. (0 setup errors, 0 hold errors)
Maximum delay is 8.446ns.
-----
```

#### Data Sheet report:

-----

All values displayed in nanoseconds (ns)

#### Pad to Pad

Source Pad	Destination Pad	Delay
In<0>	Out	8.380
In<1>	Out	8.446
S	Out	7.979

### (Data Flow Design)

```
=====
Timing constraint: TS_pad2padDF = MAXDELAY FROM TIMEGRP "inputsDF" TO TIMEGRP "outputsDF" 20 ns;
For more information, see From:To \(Multicycle\) Analysis in the Timing Closure User Guide (UG612).
3 paths analyzed, 1 endpoint analyzed, 0 failing endpoints
0 timing errors detected. (0 setup errors, 0 hold errors)
Maximum delay is 8.204ns.
-----
```

#### Data Sheet report:

-----

All values displayed in nanoseconds (ns)

#### Pad to Pad

Source Pad	Destination Pad	Delay
In<0>	Out	7.899
In<1>	Out	8.204
S	Out	7.979

### Mux 4-to-1:

```

=====
Timing constraint: TS_MUX_4to1 = MAXDELAY FROM TIMEGRP "inputs" TO TIMEGRP "outputs" 20 ns:
For more information, see From:To (Multicycle) Analysis in the Timing Closure User Guide (UG612).
6 paths analyzed, 1 endpoint analyzed, 0 failing endpoints
0 timing errors detected. (0 setup errors, 0 hold errors)
Maximum delay is 8.343ns.
=====

```

## Data Sheet report:

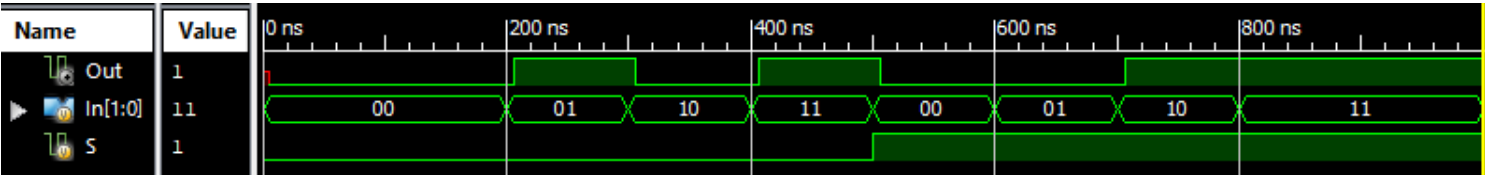
All values displayed in nanoseconds (ns)

Pad to Pad

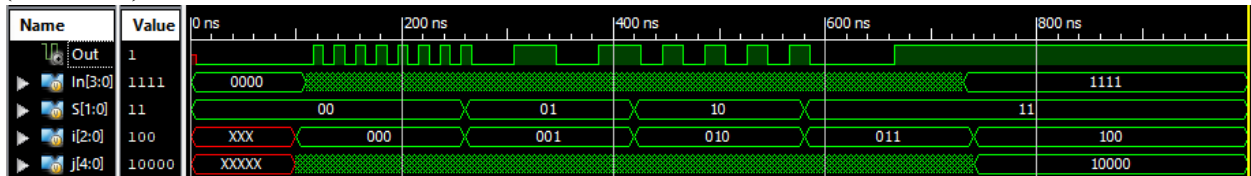
Source Pad	Destination Pad	Delay
In<0>	Out	8.124
In<1>	Out	8.046
In<2>	Out	8.343
In<3>	Out	8.309
S<0>	Out	7.951
S<1>	Out	8.120

## Post Place and Route Simulation Results

Mux 2-to-1:  
(Same for both structural and data flow designs)



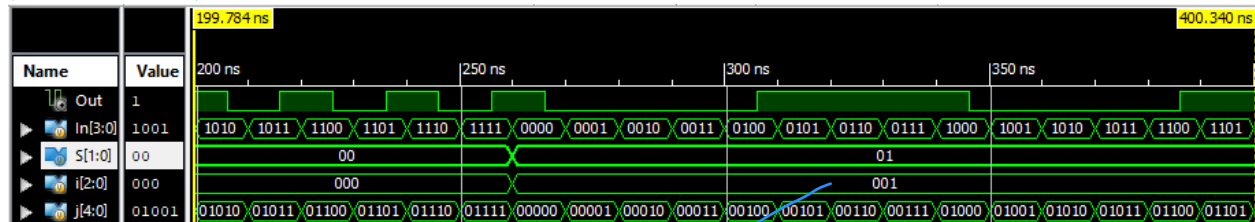
Mux 4-to-1:  
(Overview)



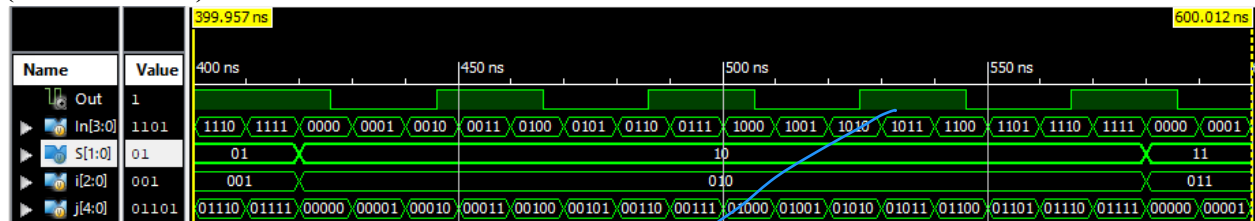
(0ns to 200ns)



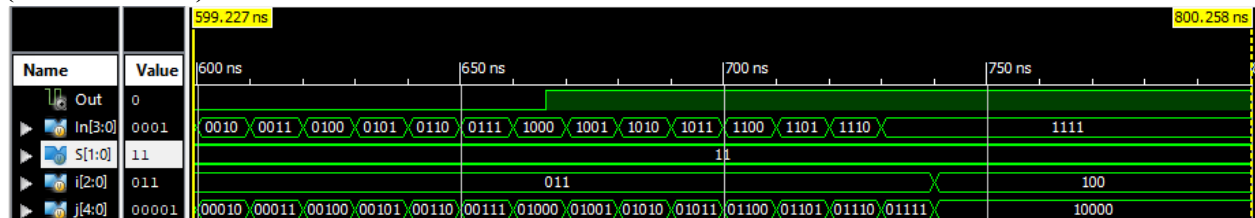
(200ns to 400ns)



(400ns to 600ns)



(600ns to 800ns)



## Power Data

Mux 2-to-1:

(Same for both structural and data flow designs)

Device		On-Chip	Power (W)	Used	Available	Utilization (%)	Supply	Summary	Total	Dynamic	Quiescent
Family	Artix7	Logic	0.000	1	63400	0	Source	Voltage	Current (A)	Current (A)	Current (A)
Part	xc7a100t	Signals	0.000	4	---	---	Vccint	1.000	0.017	0.000	0.017
Package	csg324	IOs	0.002	4	210	2	Vccaux	1.800	0.013	0.000	0.013
Temp Grade	Commercial	Leakage	0.088				Vcco33	3.300	0.005	0.001	0.004
Process	Typical	Total	0.090				Vccbram	1.000	0.000	0.000	0.000
Speed Grade	-1						Vccadc	1.710	0.020	0.000	0.020
Environment		Thermal Properties	Effective TJA (C/W)	Max Ambient (C)	Junction Temp (C)		Supply	Power (W)	Total	Dynamic	Quiescent
Ambient Temp (C)	25.0		4.6	84.6	25.4				0.090	0.002	0.088
Use custom TJA?	No										
Custom TJA (C/W)	NA										
Airflow (LFM)	250										
Heat Sink	Medium Profile										
Custom TSA (C/W)	NA										
Board Selection	Medium (10"x10")										
# of Board Layers	12 to 15										
Custom TJB (C/W)	NA										
Board Temperature (C)	NA										
Characterization											
Production	v1.0.2012-07-11										

### Mux 4-to-1:

Device		On-Chip	Power (W)	Used	Available	Utilization (%)	Supply	Summary	Total	Dynamic	Quiescent
Family	Artix7	Logic	0.000	1	63400	0	Source	Voltage	Current (A)	Current (A)	Current (A)
Part	xc7a100t	Signals	0.000	7	---	---	Vccint	1.000	0.017	0.000	0.017
Package	csg324	IOs	0.002	7	210	3	Vccaux	1.800	0.013	0.000	0.013
Temp Grade	Commercial	Leakage	0.088				Vcco33	3.300	0.005	0.001	0.004
Process	Typical	Total	0.090				Vccbram	1.000	0.000	0.000	0.000
Speed Grade	-1						Vccadc	1.710	0.020	0.000	0.020
Environment		Thermal Properties	Effective TJA (C/W)	Max Ambient (C)	Junction Temp (C)		Supply	Power (W)	Total	Dynamic	Quiescent
Ambient Temp (C)	25.0		4.6	84.6	25.4				0.090	0.002	0.088
Use custom TJA?	No										
Custom TJA (C/W)	NA										
Airflow (LFM)	250										
Heat Sink	Medium Profile										
Custom TSA (C/W)	NA										
Board Selection	Medium (10"x10")										
# of Board Layers	12 to 15										
Custom TJB (C/W)	NA										
Board Temperature (C)	NA										
Characterization											
Production	v1.0.2012-07-11										

## Conclusions

After following the procedures given, several multiplexor designs were created and tested to ensure correct operations through-simulations, timing analysis, and then implemented upon the Nexys4FPGA board[1]. As for errors, some difficulties arose when downloading the program to the board, reading the Introduction to FPGA[2] manual gave clarity to our problem and then it was promptly solved.

## References



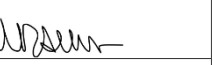
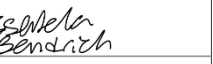
[1]: Nexys4™ FPGA Board Reference Manual, Nexys-4 rev. B; Revised November 19, 2013 by Diligent Beyond Theory

[2]: Introduction to FPGA ECE414 - Fall 2020 pdf by Randil Gajasinghe and Prof. Onur Tigli

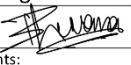
# **ECE414 Computer Organization and Design Lab Responsibility and Demonstration Sheet**

Lab #	1
Lab Description	Multiplexer Design

## Lab Responsibility Assignment

Student Name	Responsibility	Signature
Rainier Young	4x1 code and 2x1 data flow	
Brandon Rubio	4x1 code, 4x1 Simulation/Post-Map and Route Simulation Results	
Nikhem Dunkley-Allen	2x1 code Lab report	
Isabela Bendrich	2x1 code Report	

## Lab Demonstration

Teaching Assistant Signature	Date
	16-09-22
Comments: Demonstration shown - (16-09-22) Fri Batch.	